Product data sheet

1. General description

Planar passivated high commutation three quadrant triac in a SOT226A (I2PAK) plastic package intended for use in circuits where high static and dynamic dV/dt and high dl/dt can occur. This "series CT" triac will commutate the full RMS current at the maximum rated junction temperature $(T_{j(max)} = 150 \, ^{\circ}\text{C})$ without the aid of a snubber. It is used in applications where "high junction operating temperature capability" is required.

2. Features and benefits

- · 3Q technology for improved noise immunity
- High commutation capability with maximum false trigger immunity
- High junction operating temperature capability (T_{i(max)} = 150 °C)
- · High voltage capability
- Less sensitve gate for high noise immunity
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only
- · Very high immunity to false turn-on by dV/dt
- Package meets UL94V0 flammability requirement
- Package is RoHS compliant

3. Applications

- · Applications subject to high temperature
- Electronic thermostats (heating and cooling)
- · High power motor controls e.g. washing machines and vacuum cleaners
- · Rectifier-fed DC inductive loads e.g. DC motors and solenoids

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V_{DRM}	repetitive peak off- state voltage			-	-	600	V
I _{T(RMS)}	RMS on-state current	full sine wave; $T_{mb} \le 118 ^{\circ}\text{C}$; Fig. 1; Fig. 2; Fig. 3		_	-	12	Α
I _{TSM}	non-repetitive peak on- state current	full sine wave; $T_{j(init)} = 25 \text{ °C}$; $t_p = 20 \text{ ms}$; $Fig. 4$; $Fig. 5$		_	-	100	Α
		full sine wave; $T_{j(init)} = 25 \text{ °C}$; $t_p = 16.7 \text{ ms}$		-	-	110	Α
Tj	junction temperature			-	-	150	°C
Static characteristics							

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I _{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 100 \text{ mA}; T2+ G+;$ $T_j = 25 \text{ °C}; \frac{\text{Fig. 7}}{}$	-	-	35	mA
		$V_D = 12 \text{ V}; I_T = 100 \text{ mA}; T2+ G-;$ $T_j = 25 \text{ °C}; \frac{\text{Fig. 7}}{}$	-	-	35	mA
		$V_D = 12 \text{ V}; I_T = 100 \text{ mA}; T2- G-;$ $T_j = 25 \text{ °C}; \frac{\text{Fig. 7}}{}$	-	-	35	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	35	mA
V _T	on-state voltage	I _T = 15 A; T _j = 25 °C; <u>Fig. 10</u>	-	-	1.6	V
Dynamic cha	racteristics					
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	300	-	-	V/µs
dl _{com} /dt	rate of change of commutating current	V_D = 400 V; T_j = 150 °C; $I_{T(RMS)}$ = 12 A; dV_{com}/dt = 20 V/ μ s; (snubberless condition); gate open circuit	8	-	-	A/ms

5. Pinning information

Table 2. Pinning information

10010 211	mining in			
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		T2-71
2	T2	main terminal 2		G sym051
3	G	gate	0	Symost
mb	T2	mounting base; main terminal 2	1 2 3	
			I2PAK (SOT226A)	

6. Ordering information

Table 3. Ordering information

•						
Type number	Package					
	Name	Description	Version			
BTA312G-600CT	I2PAK	plastic single-ended package (I2PAK); TO-262	SOT226A			

7. Marking

Table 4. Marking codes

Type number	Marking code
BTA312G-600CT	BTA312G-600CT

8. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	600	V
I _{T(RMS)}	RMS on-state current	full sine wave; $T_{mb} \le 118 ^{\circ}\text{C}$; Fig. 2; Fig. 3	-	12	Α
I _{TSM}	non-repetitive peak on- state current	full sine wave; $T_{j(init)}$ = 25 °C; t_p = 20 ms; Fig. 4; Fig. 5	-	100	Α
		full sine wave; $T_{j(init)}$ = 25 °C; t_p = 16.7 ms	-	110	Α
I ² t	I ² t for fusing	t _p = 10 ms; sine-wave pulse	-	50	A²s
dl _T /dt	rate of rise of on-state current	I _G = 70 mA	-	100	A/µs
I _{GM}	peak gate current	t = 20 μs	-	2	Α
P_{GM}	peak gate power		-	5	W
P _{G(AV)}	average gate power	over any 20 ms period	-	0.5	W
T _{stg}	storage temperature		-40	150	°C
T _j	junction temperature		-	150	°C

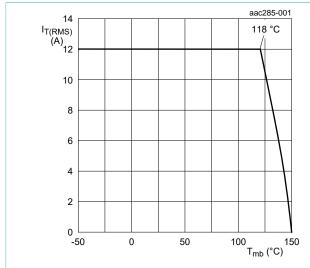


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values

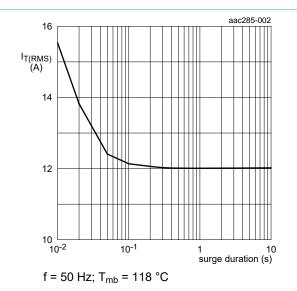


Fig. 2. RMS on-state current as a function of surge duration; maximum values

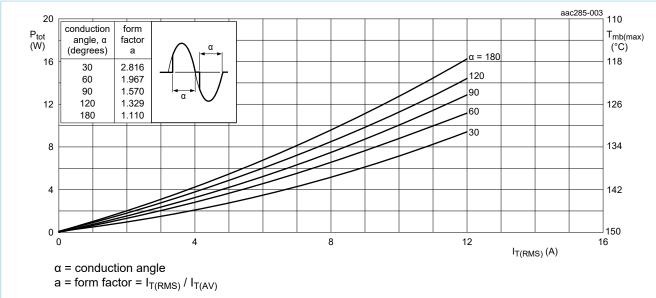


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

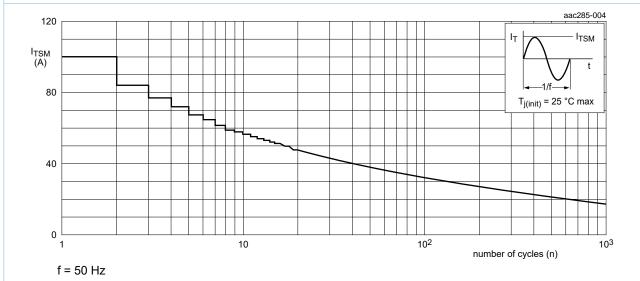
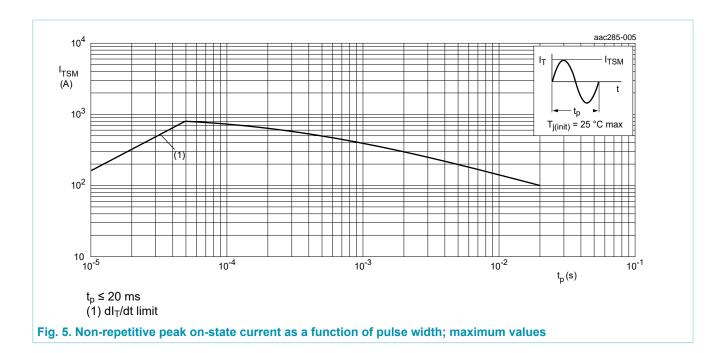


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
f	thermal resistance	half cycle; Fig. 6	-	-	2.4	K/W
	from junction to mounting base	full cycle; Fig. 6	-	-	2	K/W
R _{th(j-a)}	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W

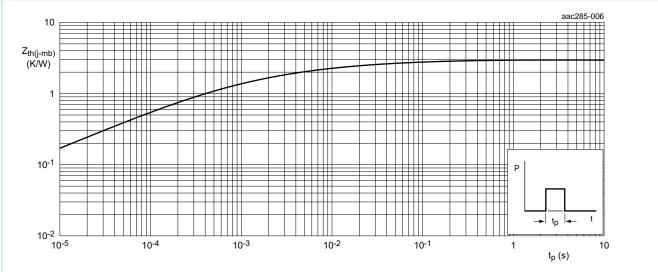


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

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10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	acteristics				-	
I_{GT}	gate trigger current	V_D = 12 V; I_T = 100 mA; T2+ G+; T_j = 25 °C; Fig. 7	-	-	35	mA
		$V_D = 12 \text{ V; } I_T = 100 \text{ mA; } T2+ \text{ G-;}$ $T_j = 25 \text{ °C; } \underline{\text{Fig. 7}}$	-	-	35	mA
		$V_D = 12 \text{ V}; I_T = 100 \text{ mA}; T2- G-;$ $T_j = 25 \text{ °C}; Fig. 7$	-	-	35	mA
L	latching current	$V_D = 12 \text{ V}; I_G = 100 \text{ A}; T2+ G+;$ $T_j = 25 \text{ °C}; Fig. 8$	-	-	50	mA
		$V_D = 12 \text{ V; } I_G = 100 \text{ A; } T2 + G-;$ $T_j = 25 \text{ °C; } Fig. 8$	-	-	60	mA
		$V_D = 12 \text{ V}; I_G = 100 \text{ A}; \text{ T2- G-};$ $T_j = 25 ^{\circ}\text{C}; \text{ Fig. 8}$	-	-	50	mA
Н	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	35	mA
V _T	on-state voltage	I _T = 15 A; T _j = 25 °C; <u>Fig. 10</u>	-	-	1.6	V
V_{GT}	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 100 \text{ mA}; T_j = 25 \text{ °C};$ Fig. 11	-	0.8	1	V
		V _D = 400 V; I _T = 100 mA; T _j = 150 °C; Fig. 11	0.2	0.45	-	V
D	off-state current	V _D = 600 V; T _j = 25 °C	-	-	10	μΑ
		V _D = 600 V; T _j = 150 °C	-	0.4	2	mA
Dynamic cl	naracteristics					
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	300	-	-	V/µs
dI _{com} /dt	rate of change of commutating current	V_D = 400 V; T_j = 150 °C; $I_{T(RMS)}$ = 12 A; dV_{com}/dt = 20 V/µs; (snubberless condition); gate open circuit	8	-	-	A/ms

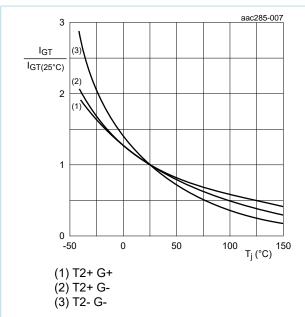


Fig. 7. Normalized gate trigger current as a function of junction temperature

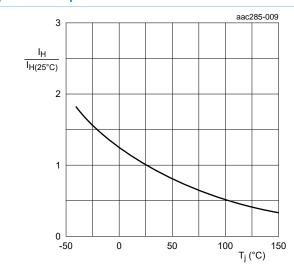


Fig. 9. Normalized holding current as a function of junction temperature

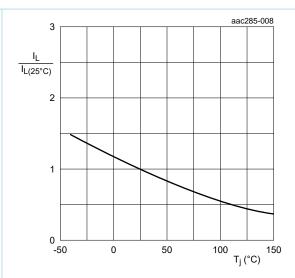
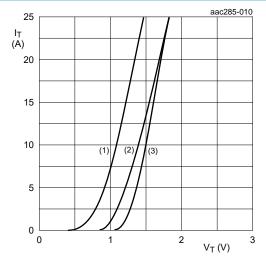
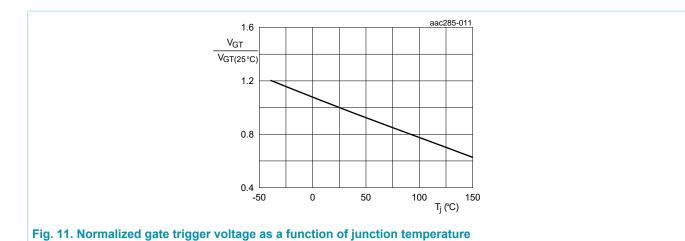


Fig. 8. Normalized latching current as a function of junction temperature

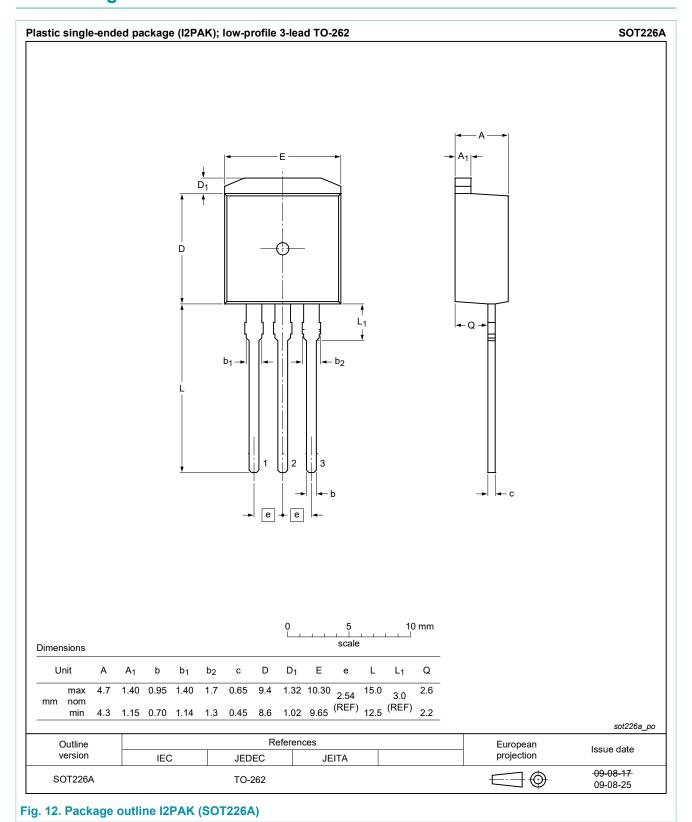


 V_o = 1.037 V; R_s = 0.034 Ω (1) T_j = 150 °C; typical values (2) T_j = 150 °C; maximum values (3) T_j = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage



11. Package outline



12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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